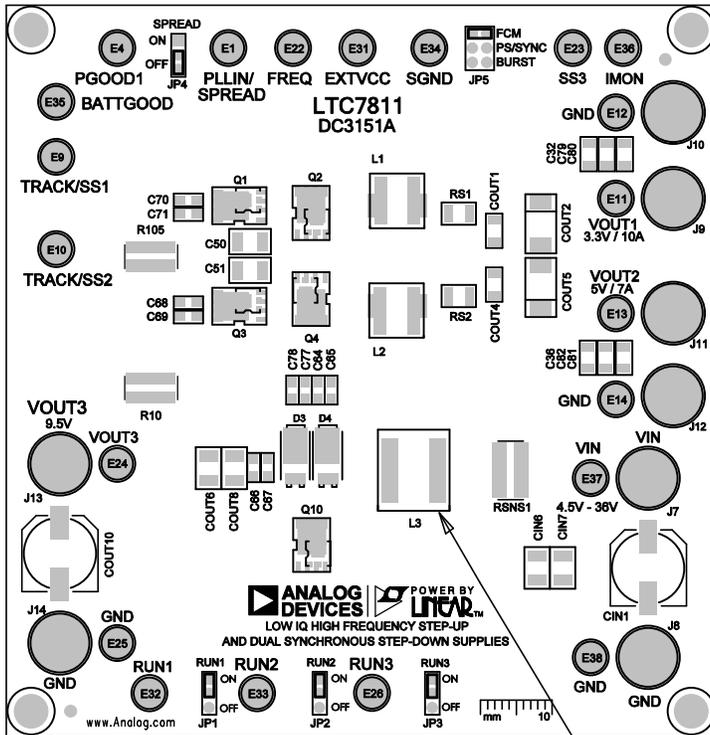


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	2	PRODUCTION	LJ	11-18-20



ANALOG DEVICES
DC3151A-2 11-18-20

TOP SILKSCREEN
TOP ASSEMBLY

SEE DETAIL A

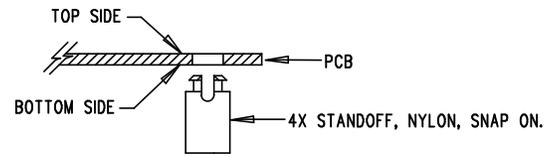
INSTALL L1, L2 AND L3 WITH THE LINE
MARKING CLOSED TO MOSFETS SIDE



DETAIL A

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



APPROVALS		ANALOG DEVICES POWER BY LINEAR™	
PCB DES.	LT	www.Analog.com FOR ADI CUSTOMER USE ONLY	
APP. ENG.	LJ	TITLE: TOP ASSEMBLY DRAWING LOW IQ HIGH FREQUENCY STEP-UP AND DUAL SYNCHRONOUS STEP-DOWN SUPPLIES	
SIZE	N/A	IC NO.	LTC7811EUJ DC3151A
SCALE = NONE	FILENAME: DC3151A-2.PCB	REV.	2
		SHT 1 OF 2	